

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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## **Panasonic**

# 6.2 mm×2.5 mm Side-operational Edge Mount Light Touch Switches

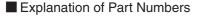
Type: **EVQP4** 

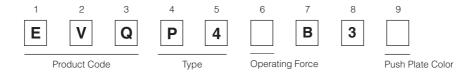


- External dimensions: 6.2 mm×2.55 mm (Excluding the push plate), Height 3.5 mm (Printed circuit board being as low as 1.35 mm)
- Side-operational Middle Travel (0.7 mm) with a high operating force (5.0 N)
- Improved soldering strength in the operating direction when mounted on PC board edge



- Operation switches for portable electronic equipment (Mobile phones, Digital still cameras, Camcorders Portable audio players, etc.)
- Keyless entry (car electronics)
- Car audio equipment





#### Specifications

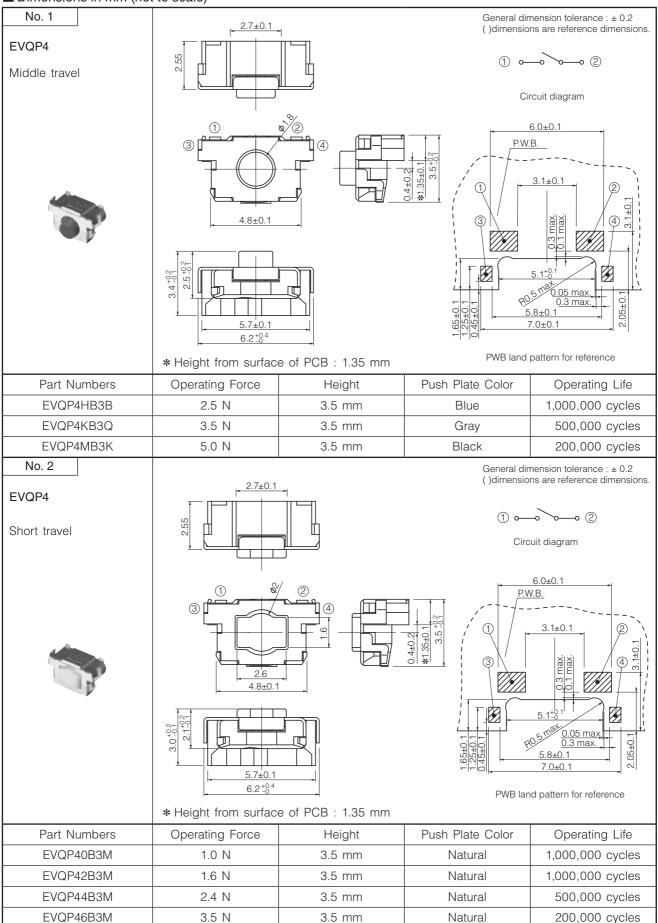
|                                 | Middle Travel  | Short Travel   |  |  |  |  |  |
|---------------------------------|--|--|--|--|--|--|--|
|                                 | Snap action / Push-on type SPST  |  |  |  |  |  |  |
| Rating                          | 10 μA 2 V DC to 20 mA 15 V DC (Resistive load)   |  |  |  |  |  |  |
| Contact Resistance              | 100 mΩ max.  |  |  |  |  |  |  |
| Insulation Resistance           | 100 MΩ min. (at 100 V DC)  |  |  |  |  |  |  |
| Dielectric Withstanding Voltage | 250 V AC for 1 minute  |  |  |  |  |  |  |
| Bouncing                        | 10 ms max. (ON, OFF)   |  |  |  |  |  |  |
| Operating Force                 | 2.5 N, 3.5 N, 5.0 N  | 1.0 N, 1.6 N, 2.4 N, 3.5 N   |  |  |  |  |  |
| Travel                          | 0.70 mm±0.2 mm   | 0.25 mm <sup>+0.05</sup> <sub>-0.15</sub> mm   |  |  |  |  |  |
| Push Strength                   | 50 N (1 minute)  |  |  |  |  |  |  |
| Operating Life                  | 2.5 N:1,000,000 cycles min.<br>3.5 N: 500,000 cycles min.<br>5.0 N: 200,000 cycles min.  | 1.0 N, 1.6 N:1,000,000 cycles min.<br>2.4 N: 500,000 cycles min.<br>3.5 N: 200,000 cycles min. |  |  |  |  |  |
| nperature                       | −40 °C to +85 °C   |  |  |  |  |  |  |
| auah wa                         | -40 °C to +85 °C (Bulk)  |  |  |  |  |  |  |
| erature                         | −20 °C to +  | -20 °C to +60 °C (Taping)  |  |  |  |  |  |
| ntity/Packing Unit              | 2,500 pcs. Embossed Taping (Reel Pack)   |  |  |  |  |  |  |
| on                              | 12,500 pcs.  |  |  |  |  |  |  |
|                                 | Rating Contact Resistance Insulation Resistance Dielectric Withstanding Voltage Bouncing Operating Force Travel Push Strength Operating Life  preparature  Perature  Intity/Packing Unit | Middle Travel  |  |  |  |  |  |

Design and specifications are each subject to change without notice. Ask factory for the current technical specifications before purchase and/or use. Should a safety concern arise regarding this product, please be sure to contact us immediately.



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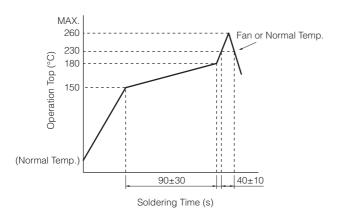
#### ■ Dimensions in mm (not to scale)



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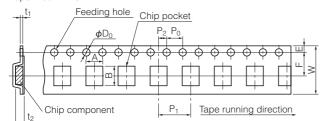
## **Panasonic**

## ■ Recommended Reflow Soldering Conditions



### Embossed Carrier Taping





Taping condition: Lack of products in the middle of taping should be one MAX, but total quantity specified in the specifications should be secured.

Peeling off strength of top tape: It should be within 0.2N to 1.0N at

Peeling off strength of top tape: It should be within 0.2N to 1.0N at 165 degree in peeling off angle.

Joint of carrier tape: One joint per one reel may exist.

Unit: mm

| Part No. | Height | А       | В       | W        | F       | Е         | P <sub>1</sub> | P <sub>2</sub> | P <sub>0</sub> | D₀ Dia.             | t1      | t2        |
|----------|--------|---------|---------|----------|---------|-----------|----------------|----------------|----------------|---------------------|---------|-----------|
| EVQP4    | 3.5    | 6.5±0.2 | 3.9±0.2 | 12.0±0.3 | 5.5±0.1 | 1.75±0.10 | 8.0±0.1        | 2.0±0.1        | 4.0±0.1        | 1.5 <sup>+0.1</sup> | 0.4±0.1 | 3.75±0.20 |

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